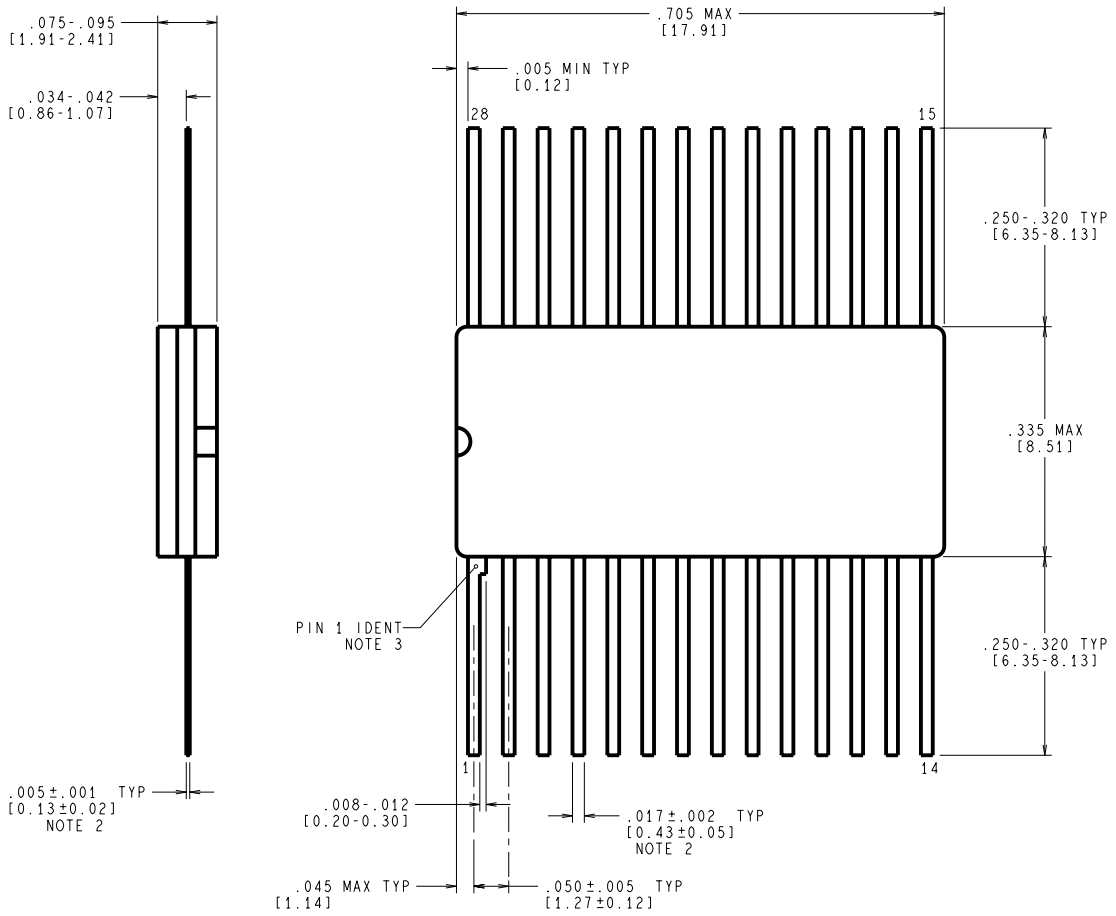
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
D	REVISE AND REDRAW PER CURRENT STANDARD; UPDATE TITLE & MIL/AERO STAMP.	11047	07/14/95	MS/



CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO A MINIMUM THICKNESS OF 200 MICROINCHES/ 5.08 MICROMETERS. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE.
2. LEAD THICKNESS MAY BE INCREASED BY .003 INCHES/ 0.08 MILLIMETERS MAXIMUM AFTER LEAD FINISH APPLIED.
3. LEAD 1 IDENTIFICATION SHALL BE:
   a) A NOTCH OR OTHER MARK WITHIN THIS AREA
   b) A TAB ON LEAD 1, EITHER SIDE
4. REFERENCE JEDEC REGISTRATION MO-019, VARIATION AD, DATED 9/20/77.

MIL-PRF-38535
CONFIGURATION CONTROL

APPROVALS	DATE
DRAWN: MARTA SUCHY	07/14/95
DFTG. CHK.	
ENGR. CHK.	

National Semiconductor
2900 Semiconductor dr, Santa Clara, CA 95052-8090

CERPAC, 28 LEAD

PROJECTION
INCH [MM]

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	MKT-W28A	D

DO NOT SCALE DRAWING | SHEET 1 of 1